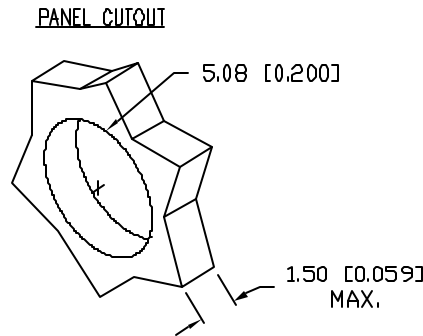
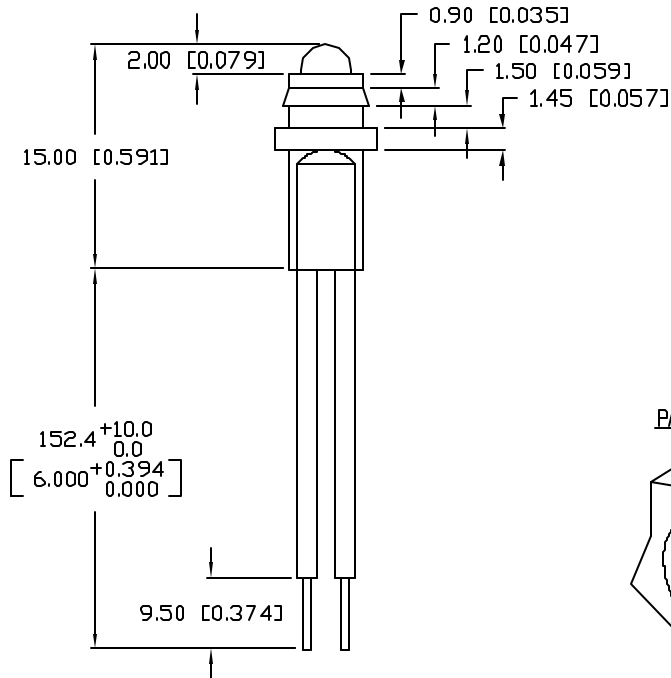
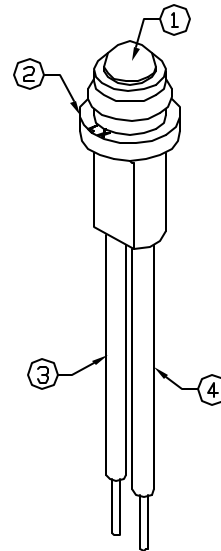
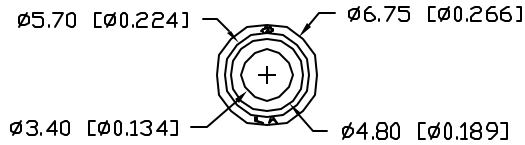


UNCONTROLLED DOCUMENT

PART NUMBER		REV.
SSI-RM3091SUGD-150		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11317.	3.17.06



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		574		nm	
FORWARD VOLTAGE		2.2	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		50		med	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	GREEN DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/ $^{\circ}\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^{\circ}\text{C}$

* $t < 10\mu\text{s}$

NOTES:

- SSL-LX306F4SUGD, GREEN LED.
- SSH-RM3091, BLACK RUBBER HOUSING.
- ANODE LEAD: LXP-WST26RDT0C, 26 AWG STRANDED, RED INSULATION, CUT 160mm LONG, STRIP 2mm & 9.5mm.
- CATHODE LEAD: LXP-WST26BLT0C, 26 AWG STRANDED, BLACK INSULATION, CUT 160mm LONG, STRIP 2mm & 9.5mm.
- CRIMP OR SOLDER WIRE LEADS TO LED LEADS.

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= ^{+DECIMAL PRECISION} -0.00 ^{MAX.= +0.00} -DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV.	PART NUMBER
A	SSI-RM3091SUGD-150

CONFIDENTIAL INFORMATION
 THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC, THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.



290 E. HELEN ROAD
 PALATINE, IL 60067-6976
 PHONE: +1.847.359.2790
 US WEB: www.lumex.com
 TW WEB: www.lumex.com.tw

T-3mm 574nm AlInGaP GREEN LED PANEL INDICATOR,
 GREEN DIFFUSED LENS, 6" WIRE LEADS.

RELIABILITY NOTE
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE:
GT			4.5.02
			PAGE: 1 OF 1
			SCALE: N/A